ABSTRACT OF THE DISCLOSURE

SYSTEMS AND METHODS FOR MODULATING STEP COVERAGE DURING CONFORMAL FILM DEPOSITION

Systems and methods for processing a substrate include a) arranging a substrate on a pedestal in a processing chamber; b) supplying precursor to the processing chamber; c) purging the processing chamber; d) performing radio frequency (RF) plasma activation; e) purging the processing chamber; and f) prior to purging the processing chamber in at least one of (c) or (e), setting a vacuum pressure of the processing chamber to a first predetermined pressure that is less than a vacuum pressure during at least one of (b) or (d) for a first predetermined period.

FIG. 1